

# Siconnex BATCHSPRAY® Acid: Efficiency has a name.



Siconnex BATCHSPRAY® Acid is designed for acids and bases. It can be loaded manually or combined with Siconnex BATCHSPRAY® Autoload and the patented Retainer Comb Handling (RCH) System. The equipment is completely closed, which means the operator is protected from direct contact with any chemicals. This makes the process safe and also environmentally friendly. Siconnex BATCHSPRAY® Acid can process wafer sizes from 50 mm to 300 mm.



## ADVANTAGES

- Automated dry-in, dry-out process
- Five processes possible in one sequence
- Repeatability thanks to process control
- Equipment footprint of 1.2 m x 2 m
- Up to 80% less DI water
- Up to 80% reduction in process media
- Closed system
- User safety
- Chemical mixing management system



**BATCHSPRAY®**  
**ACID**

## ETCH

- Metal Etch (Al, Cu, Ti, Au, Ni,...) with End Point Detection
- III/V Etch (GaAs, AlGaAs, InGaP,...)
- Oxide Etch
- Freckle Etch
- Silicon Etch
- Ge Etch
- Nitride Etch
- UBM Etch
- Glass Etch

## CLEAN

- SicOzone Clean
- SicOzone + Ultra Diluted Clean Applications
- Contact Cleans
- Organic Removal & Clean
- Etch Residue Clean
- Post Ash Residue Clean
- HF Last
- Prediffusion Cleans
- Field Cleans (Organic & Inorganic Cleans)

## RESIST STRIP

- SicOzone Strip
- Positive and Negative Resist Strip
- Implanted Photo Resist Strip
- Enhanced Strip
- Resist Rework

## THE SICOZONE-PROZESS

- Cleans and strips resist from substrates.
- No need for expensive solvents that are harmful to health.
- Ozone is cheap to produce from oxygen.